SUPPORTING INFORMATION

High Performance, 3D-Printable Dielectric Nanocomposites for Millimeter Wave Devices

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Table S1. Tabulated rheological properties of the polymeric inks used in this study.

Formulation	Yield Stress (Pa)*	G'/G" @ 10 rad/s, 1% Strain	η at low shear bound (Pa*s)	Thinning Threshold (rad/s)	log(η)/log(γ'), thinning region
1a	5.73E+03	1.00	1.02E+05	2.52E-03	-0.543
1b	1.34E+04	1.29	2.16E+05	<1E-3	-0.546
1c	3.27E+03	0.93	4.81E+04	<1E-3	-0.528
1d	6.63E+03	1.02	2.80E+05	<1E-3	-0.660
1e	1.39E+03	0.90	1.03E+05	<1E-3	-0.520
1f	1.53E+03	1.47	7.59E+04	<1E-3	-0.650
2a	7.84E+02	0.91	3.50E+04	<1E-3	-0.539
2b	8.88E+02	1.53	1.70E+04	1.00E-02	-0.660
2c	1.97E+03	1.79	5.99E+04	1.58E-03	-0.596
2d	7.88E+02	1.14	1.32E+04	<1E-3	-0.533
2e	1.69E+03	1.65	8.05E+04	<1E-3	-0.578
2f	1.53E+03	1.47	7.59E+04	<1E-3	-0.650
3a	1.22E+03	0.97	1.29E+04	<1E-3	-0.369
3b	1.36E+03	1.07	3.18E+04	<1E-3	-0.595
3c	1.51E+03	1.24	6.00E+04	<1E-3	-0.537